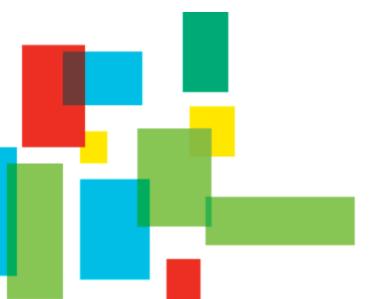
Printed Electronics

Sun Chemical/DIC Advanced Materials Group

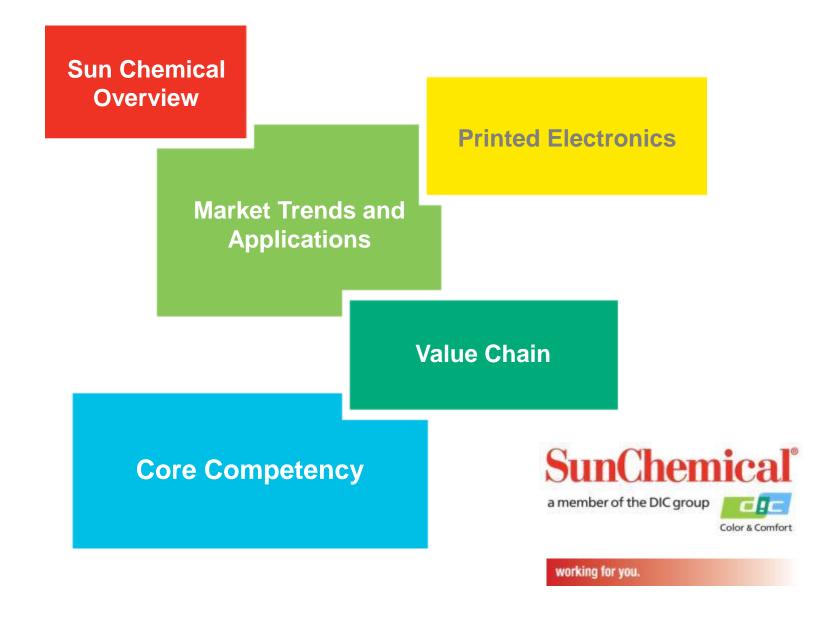




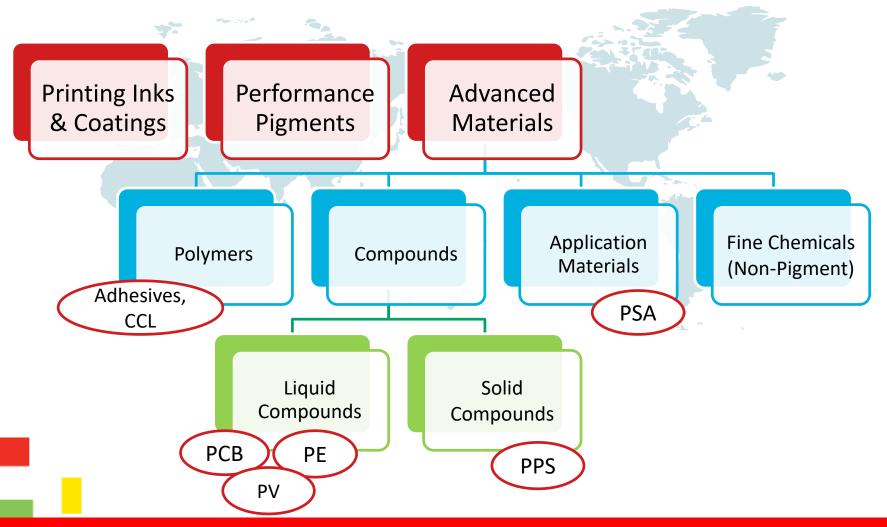
working for you.



Outline



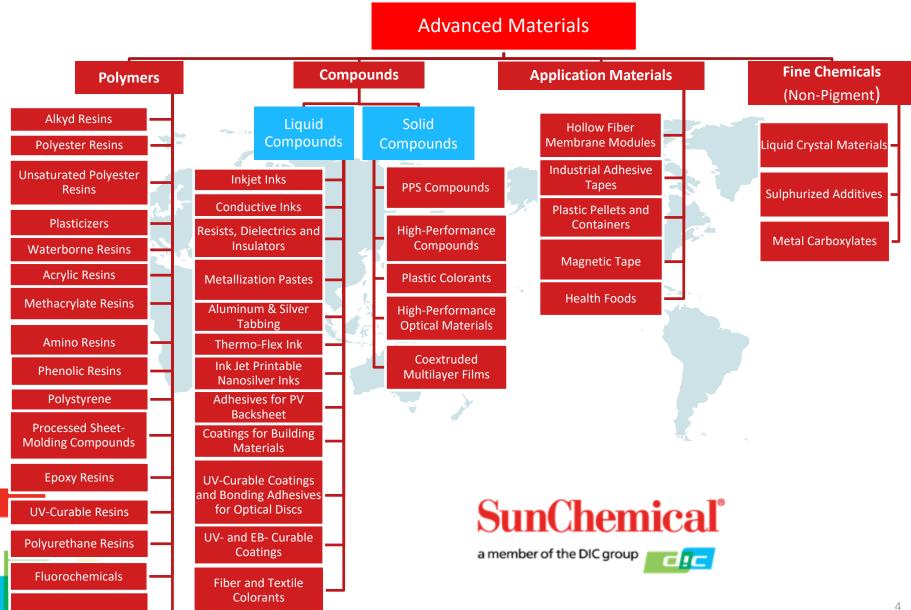
DIC/Sun Chemical Advanced Materials Group by Product Groups



Sun Chemical's global presence, combined with advanced technologies and products from Sun & DIC, allows for the delivery of local service and support with *Solutions*. Tailor-Made:

Sun Chemical Advanced Materials Products:

Alkylphenols



Sun Chemical Electronic Materials Main Market Segments

Inks for Printed Circuit Board

- Solder mask, etch and plating resists, legend inks, etc.
- Rigid and Flex PCBs



Inks for Solar Market

- Solvent, UV and hot melt plating and etch resists
- Advanced PV technologies

Inks for Printed Electronics

- Conductive and dielectric inks
- Etch resists
- Diverse range of material needs for diverse range of applications







Printed Electronics

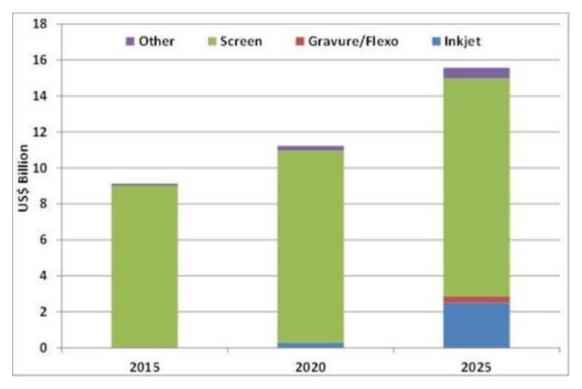
The basic value proposition for printed electronics is that by using additive processes, instead of subtractive processes, you can lower complexity and cost of manufacture.

Markets at different levels of maturity, revenue, profitability and growth

Conductive Ink Market

- At about \$2.3 Billion in 2015 dominated by front side silver paste for solar metallization, followed by printed bezels for touch panels (tablets and phones)
- Overall growth at 3.3% CARG in 2020

total value of printed components split by printing technology type



Source: IDTechEx



Combination for Success



Printed Electronics Value Chain

Complete Industry Value Chain for the Printed Electronics Industry

	Substrates & Inks	Printing Equipment	Functional Components (Displays, batteries, sensors, transistors)	Technology Integrators & Manufacturers (Traditional & PE)	End Products Using Printed Electronics ("Smart" products with functionality)
	Technology Developers	Technology Developers	Technology Developers	Technology Developers	Product & Brand Developers
	Ink/Substrate Manufacturers	Equipment Manufacturers	Component Producers	Manufacturers	End Product Manufacturer
,	Ink/Substrate Customers	Equipment Customers	Component Customers	Customers	End Product Customers

Source: http://www.aistrupconsulting.com



Sun Chemical brings together key partners in the value chain to lower risk and increase rate of success

Electronics Market trends favoring Printed Electronics

Touch Sensing

Touch switches/panels being integrated into everyday devices

Structural electronics

Molded interconnects, 3D antenna, In-mold Electronics

Tracking, security and identification

 High speed printing directly on label or packaging with conductive inks, inventory control

Interactivity

Smart packaging and labels with printed sensors, games and toys,

Wearable electronics

With sensors integrated directly into textile garments or bands.

Energy harvesting and storage

Integrated flexible PVs and printed batteries

Internet of Things

- Smart homes and cities
- Connection and communication of everyday devices enabled by printed electronics.

Touch Sensing

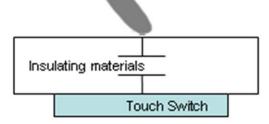
used in devices requiring switches, sliders, scrollers, touchpads, or their combinations

Target Markets

- Appliances
- Consumer electronics
- Automotive
- Industrial controls
- Heatlhcare

Sun Chemical offers and develop advanced solutions for touch sensing

- conductive and dielectric inks,
- fine line printable silvers for transparent electrodes (50 microns capable)
- nanosilver based inkjet and screen printable for low profile and high conductivity
- DIC's Pressure sensitive adhesives
- Partner with touch sensor technology developers to develop integrated solutions



Electric conduction between finger and touch switch creates a field of capacitance that triggers the on/off switch.

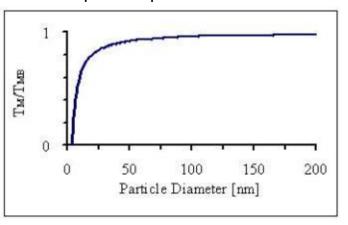




Suntronic Nanosilver for Printed Electronics

PROPERTY	EMD5730	EMD5800 and 5805	
Silver Content	40%	48-65%	
Binder	Solvent-based	Oil-based	
Particle Size	50 nm	7 nm	
Print Process	Inkjet	Inkjet, aerosol jet, dispense, screen	
Volume Resistivity	10 – 30 uΩ.cm	4 – 30 uΩ.cm	
Sintering Temperature	150 - 250°C	80 - 150°C	

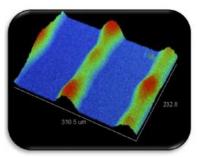
Melt point depression



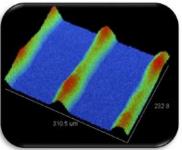
- New nanosilver product line
- Superior conductivity
- Reduced sintering time and temperature
- Digital or high speed roll to roll

Fine line solutions for Touch Sensing

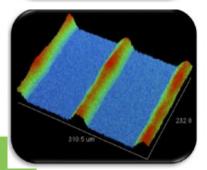
Screen printed nominal 50 micron wide lines ASADA mesh/WCPC



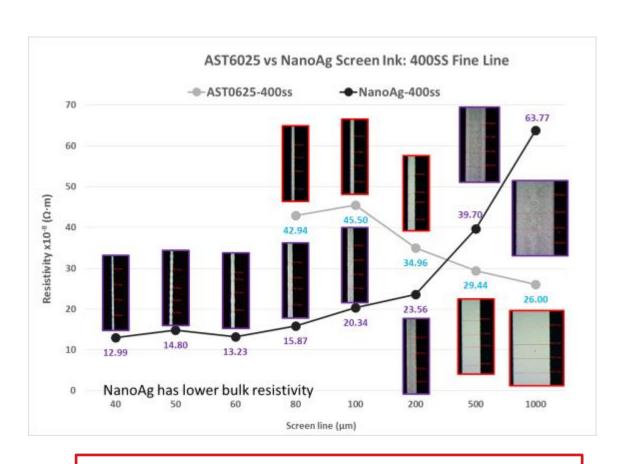
290 mesh 62 microns



400 mesh 56 microns



500 mesh 49 microns



- Considering 100 micron line width: 20 microns thick for AST6025 vs 8 microns thick for nanoAg ink
- Resistivity >50% lower for nanosilver ink
- Same resistance can be achieved with ~5x less thickness



Printed Antenna for Mobile Devices

- Today's mobile devices have higher # of antennas, more complex designs, thinner devices, integrated sensors and other components
- Pressure on time-to-market, cost, supply chain and ease of integration, innovation and differentiation



- Mature technology
- High performance
- Design restricted materials (mostly ABS, and black), No LDS will image directly on covers or chassis
- Development time consuming 6h plating step only
- Production complex supply chain and logistics, environmentally not friendly



- Design freedom wide range of plastics and colors
- Development Reduced time for prototyping **Production - simplified & environmentally friendly**
- In development
- Ease of adaptation?

Direct write methods for additive structuring on 3D parts

Source: www.fluidant.com

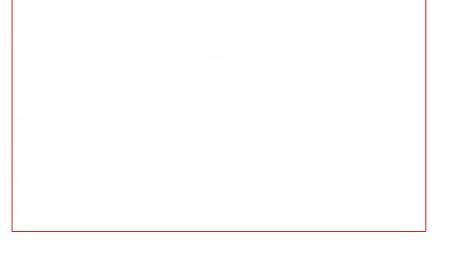
Direct patterning on 3D surfaces - fluid development in partnership with equipment manufacturer

Dispensing





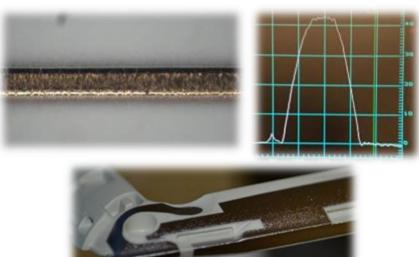






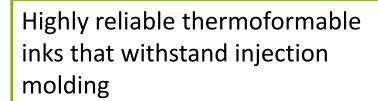


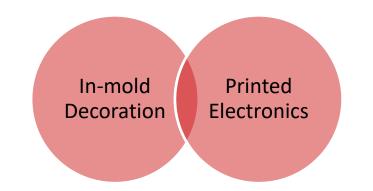




In-mold Electronics (IME)

- More ergonomic, thinner parts (no need for dead space), lighter weight (>70% lighter)
- Less expensive manufacturing process by replacing wiring with printed traces and printed devices, less raw materials
- Less assembly
- Less moving parts to fail or wear out
- Durability, total encapsulation of printed switches
- More design freedom









Source: Tactotec

Target markets:

- Automotive interiors
- Appliances
- Consumer electronics
- Wearables
- Medical devices

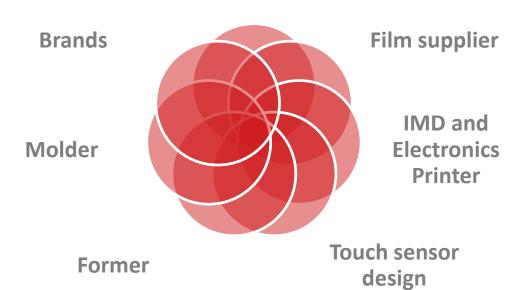


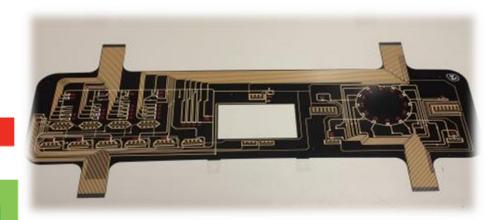
Sun Chemical/DIC Core Competency for IME

- Sun Chemical is one of the main suppliers of graphic inks to IMD for appliances, automotive and packaging applications.
- Graphic ink product portfolio includes SB and UV curable thermo-formable and moldable solutions for first and second surface molding.
- Adhesion promoters for various molten plastics used in appliances and automotive sectors
- Strong relationships with across value chain for IMD
- IME conductive and dielectric inks near commercialization
- Combining IMD graphic inks and fully compatible IME electronic materials, Sun Chemical gains advantage as a full solution provider.
- Enabling production of fully decorated and multilayer in-mold electronics.

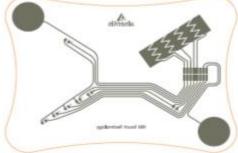
In-mold Electronics Cont'd

IMD/IME ink supplier



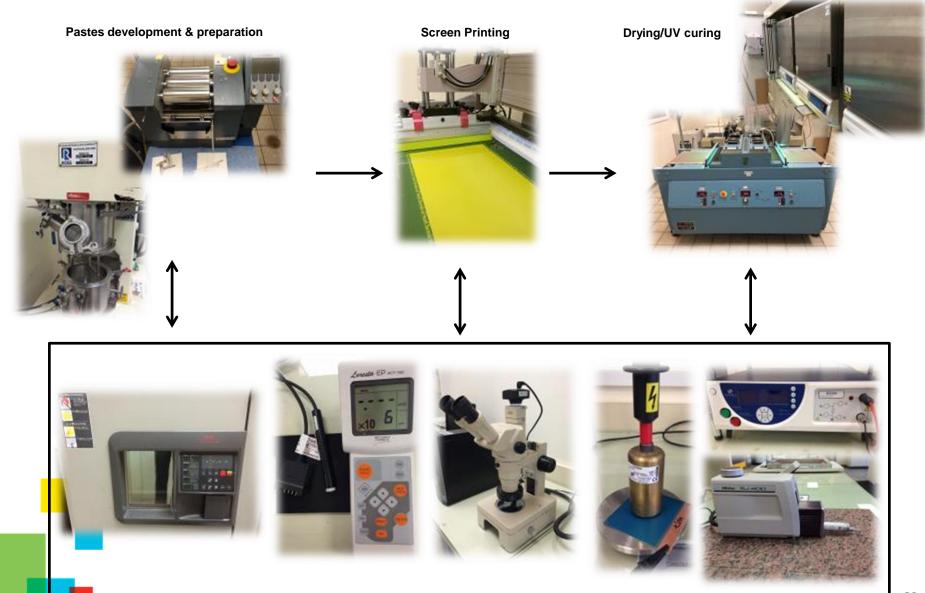








Electronic Materials R&D and Application Development Laboratory



Sun Chemical- AMG Electronic Materials Portfolio

our chemical Airio Electronic Materials i Ortiono						
Printing Method	Product Type	Drying/ Curing	Filler	Features	Status	Applications
Flexo	Conductors/ Insulators	Thermal	PTF Silver/ Graphite/ Dielectrics	Waterbased/ UV	Commercial (AMG)	Printed antenna (2D), smart label, Touchcode, RFID
Screen	Conductors/ Insulators	Thermal	PTF Silver/ Graphite/ Dielectrics	Solvent / UV	Commercial (AMG)	RFID, Human Machine Interface, membrane touch switch, circuits
Screen	Conductors/ Insulators	Thermal	PTF Silver/ Dielectrics/	Solvent/ UV	Development (AMG)	In-Mold Electronics, switches, circuits

Solvent

Solvent

Wax

UV

Oil based/

Solvent

Oil based

Oil based

based

Commercial

Commercial

Commercial

Commercial

Commercial

Development

Development

(AMG)

(AMG)

(AMG)

(AMG)

(AMG)

(AMG)

(AMG)

Printed 3D antenna - Pulse

Printed antenna, circuits

Printed conductor, circuits,

Printed 3D antenna, sensors

Printed antenna, RFID,

circuits, sensors

Photovoltaics

Photovoltaics

OPV

Graphics

PTF Silver/ Graphite/

Dielectrics/nanosilver

Dielectric-none

Dielectric-none

Dielectric-none

Nanosilver

Nanosilver

Nanosilver

Thermal

Thermal

Thermal

Freezing

Thermal

Photonic

Thermal

Photonic

Thermal

Photonic

UV

Conductors/

Insulators

Etch Resist

Etch Resist

Insulators

Conductors

Conductors

Conductors

Dispense

Screen

Inkjet

Inkjet

Inkjet

Aerosol

Screen

jet

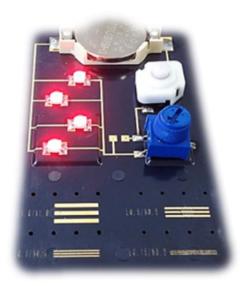


Molded Interconnects

- Laser Direct Structuring is a commonly used MID technology. The 3D circuit carrier is injection molded from a modified compound which allows for laser activation and the successive metallization of the conductor tracks on the surface.
- DIC has recently launched the world's first LDS-PPS resin, which bridges the gap between conventional engineering plastics, such as nylon, to more expensive hightemperature polymers, including LCP or PEEK



Metallized Sample Plate



3D Structured Electronic Circuit



Smart Packaging (interactive and intelligent packaging)

 Enables personalized interaction and information exchange between products and consumers

• Elements: Source: HOLST Centre



Main Applications:

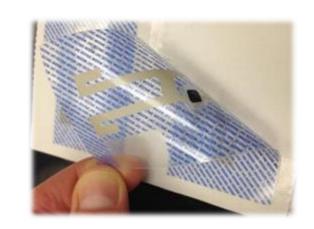
Pharma - provide interaction and prompting, reinforcement and cueing, tracking patient's adherence, send text message reminders, collect data about patient satisfaction, etc.

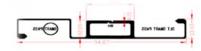
Food – Active and intelligent packaging

- Food safety in various applications (dairy products, meat and poultry, ready-to-eat meals), Oxygen or ethylene scavengers, moisture absorbers
- Temperature or time monitoring

Smart and Security Labels - RFID

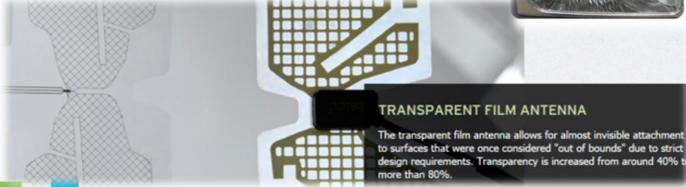
- Smart labels typically use some form of RFID.
- RFID Labels key driver is traceability of an item from manufacture to sale and even beyond.











Smart and Interactive Print at Sun Chemical/DIC

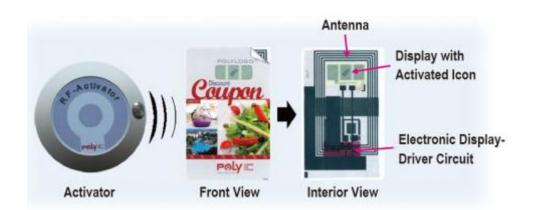
Core Competency

- "the world's largest producer of printing inks"
- Expert knowledge of packaging market and liquid inks technologies
- Large customer base from small shops to biggest packaging companies
- We are well established within packaging value chain
- We already have conductive technologies and core knowledge to develop further if application demands
- Dedicated group for CPG
- Partnering across value chain
- Main focus on application development and integration
 - NFC enabled packaging, wireless communication, printed sensors integration, light up packaging, interactive shelfs, wireless power, etc.

Smart Cards – payment, ID, security, transport, ticketing

Contactless cards

- Does not have a battery and instead is powered by the RF wave emitted by the reader.
- The embedded antenna works as an RF power collector.
- The chip is connected to this antenna to receive power and to communicate with the reader.





Sun Chemical/DIC – well established within value chain for plastic cards – supplying graphic inks, conductive inks, mag tape, etc.

Source: ASK-RFID, PolyIC



Wearable Electronics

- Smart Clothing and e-Textiles
 - surge in interest, funding and R&D since 2014
- Medical and healthcare devices
 - hearing aids, diabetes management, cardiovascular monitoring, and clinical trial sensors, skin patches, smart bandaids, leak detection sensors, temperature sensors
- Smart watches, activity and fitness trackers





Medtronic's Seeq heart monitoring device Image Source: Medtronic

00:24:55

Stretchable, durable and wash resistant inks, coatings and adhesives







Source: IDTechEx

Core Competency

- DIC/Sun Chemical is full solution provider fully decorated printed electronics
 - Strong foundation in relevant technologies
 - materials for graphics printing, electronics printing, assembly and packaging
 - expertise in ink design, testing and application development
- Continuous investment into R&D and innovation
 - Capabilities internally or through partnerships to design and make prototypes
 - Materials development focusing on new trends
 - Focus on sustainable solutions
 - New revenue opportunities for customers
 - IP development
- Strong presence within value chain
- Strategic partnerships and acquisitions

Sun Chemical is a partner that transforms with you

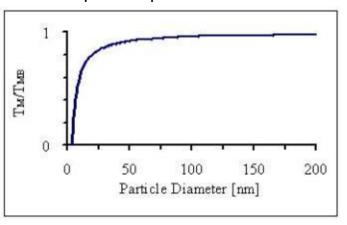
October 25, 2016
Sun Chemical and the DIC Corporation
Acquire Gwent
Electronic Materials
Ltd.

Suntronic Nanosilver for Printed Electronics

PROPERTY	EMD5730	EMD5800 and 5805	
Silver Content	40%	48-65%	
Binder	Solvent-based	Oil-based	
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Volume Resistivity	10 – 30 uΩ.cm	4 – 30 uΩ.cm	
Sintering Temperature	150 - 250°C	80 - 150°C	



Melt point depression



- New nanosilver product line
- Superior conductivity
- Reduced sintering time and temperature
- Digital or high speed roll to roll

Our commitment Quality. Service. Innovation.

Quality

Comprehensive and consistent offering of world-class products, services, and solutions that save time and money.

Service

Our world-class technical and customer service consistently delivers on our promises and collaborates with customers to deliver solutions that solve their unique challenges.

Innovation

With 13 research and development centers, Sun Chemical averages two patents per month with regular breakthroughs in ink, pigment, and application material technology.





Sun Chemical EM Solutions

